

IN THE CLAIMS:

Please amend the claims as follows:

- 1-12. *(canceled)*
13. *(currently amended)* A mobile phone comprising:
 - a system for analysing connection conditions between an integrated circuit package within said mobile phone and a circuit board within said mobile phone, said system comprising:
 - coupling elements coupling said integrated circuit package electrically to said circuit board, and
 - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
 - conductors configured to electrically connect at least two of said support elements with each other on the side of the integrated circuit package,
 - ~~measuring means~~ a measurement device arranged at said support elements and configured to pick-off physical values between said support elements, and
 - ~~evaluation means~~ a determination device configured to evaluate said physical values to determine mechanical properties of said support elements, and configured to conclude a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
14. *(previously presented)* The mobile phone of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.

15. (*previously presented*) The mobile phone of claim 13, wherein said support elements are solder pads.
16. (*previously presented*) The mobile phone of claim 13, wherein said support elements are arranged adjacent to said coupling elements.
17. (*previously presented*) The mobile phone of claim 13, wherein said support elements are arranged semicircular along said coupling elements.
18. (*previously presented*) The mobile phone of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
19. (*previously presented*) The mobile phone of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.
20. (*currently amended*) The mobile phone claim 13, wherein said ~~means provide measurement device provides~~ picking-off electrical conditions of said support elements.
21. (*currently amended*) The mobile phone claim 13, wherein said ~~means provide measurement device provides~~ picking-off mechanical conditions of said support elements.
22. (*currently amended*) The mobile phone of claim 13, wherein ~~a storage means are comprised to store stores~~ said picked-off physical values.
23. (*currently amended*) The mobile phone of claim 13, wherein said evaluation

~~means compare determination device compares~~ said picked-off physical values with comparative values to determine connection condition.

24. *(currently amended)* The mobile phone of claim 13, wherein said ~~evaluation means provide determination device provides~~ an error message in case a poor connection condition is determined.
25. *(currently amended)* The mobile phone of claim 13, wherein said error message is stored within said storage [[means]].
26. *(previously presented)* The mobile phone of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.

27-29. *(canceled)*

30. *(currently amended)* An apparatus comprising:
 - coupling elements coupling an integrated circuit package electrically to a circuit board,
 - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
 - conductors configured to electrically connect at least two of said support elements with each other on the side of the integrated circuit package,
 - ~~measuring means a measurement device~~ arranged at said support elements and configured to pick-off physical values between said support elements, and
 - ~~evaluation means a determination device~~ configured to evaluate said physical values to determine mechanical properties of said support elements, and configured to conclude a condition of said electrical coupling of said integrated

circuit package with said circuit board from said determined mechanical properties of said support elements.

31. *(previously presented)* The system of claim 30, wherein said support elements are arranged semicircular along said coupling elements.
32. *(previously presented)* The apparatus of claim 30, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
33. *(previously presented)* An apparatus comprising:
 - coupling elements coupling an integrated circuit package electrically to a circuit board, and
 - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
 - means for electrically connecting at least two of said support elements with each other on the side of the integrated circuit package,
 - measuring means arranged at said support elements for picking off physical values between said support elements, and
 - evaluation means for evaluating said physical values to determine mechanical properties of said support elements, and for concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
34. *(previously presented)* The apparatus of claim 33, wherein said support elements are arranged semicircular along said coupling elements.